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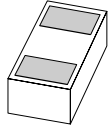
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BB187LX

VHF variable capacitance diode

Rev. 01 — 19 February 2009

Product data sheet

1. Product profile

1.1 General description

The BB187LX is a planar technology variable capacitance diode in a SOD882T ultra small leadless plastic SMD package. The excellent matching performance is achieved by gliding matching and a Direct Matching Assembly (DMA) procedure.

1.2 Features


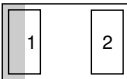

- High linearity
- Excellent matching to 2 % DMA
- Ultra small leadless SMD package
- $C_{d(25V)}$: 2.75 pF; $C_{d(2V)}$ to $C_{d(25V)}$ ratio: 11
- Low series resistance

1.3 Applications

- Voltage Controlled Oscillators (VCO)
- Electronic tuning in VHF television tuners

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	
2	anode		

Transparent top view

[1] The marking bar indicates the cathode.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BB187LX	-	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882T

4. Marking

Table 3. Marking codes

Type number	Marking code
BB187LX	L8

5. Limiting values

Table 4. Limiting values

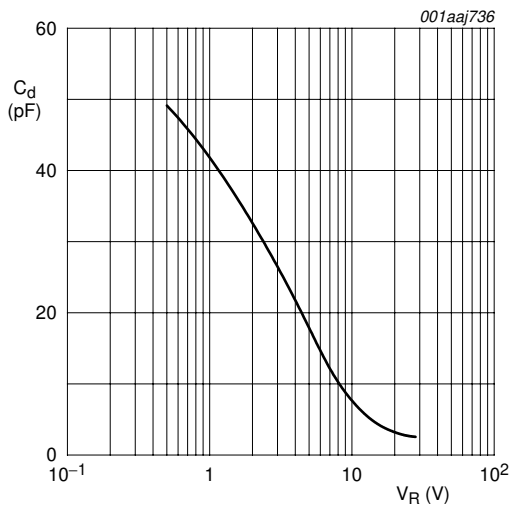
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	32	V
I_F	forward current		-	20	mA
T_{stg}	storage temperature		-55	+150	°C
T_j	junction temperature		-55	+125	°C

6. Characteristics

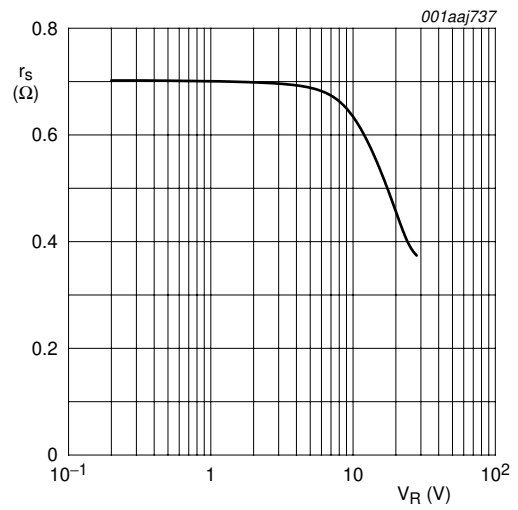
Table 5. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_R	reverse current	see Figure 3				
		$V_R = 30$ V	-	-	10	nA
		$V_R = 30$ V; $T_j = 85$ °C	-	-	200	nA
r_s	diode series resistance	$f = 470$ MHz at $V_R = 5$ V; see Figure 2	-	0.7	-	Ω
C_d	diode capacitance	$f = 1$ MHz; see Figure 1 and Figure 4				
		$V_R = 2$ V	29.3	-	34.2	pF
		$V_R = 25$ V	2.57	2.75	2.92	pF
$C_{d(2V)}/C_{d(25V)}$	diode capacitance ratio (2 V to 25 V)	$f = 1$ MHz	11	-	-	
$\Delta C_d/C_d$	diode capacitance matching	$V_R = 1$ V to 25 V; in sequence of 5 diodes (gliding)	-	-	2	%



$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 1. Diode capacitance as a function of reverse voltage; typical values



$f = 470 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}.$

Fig 2. Diode serial resistance as a function of reverse voltage; typical values

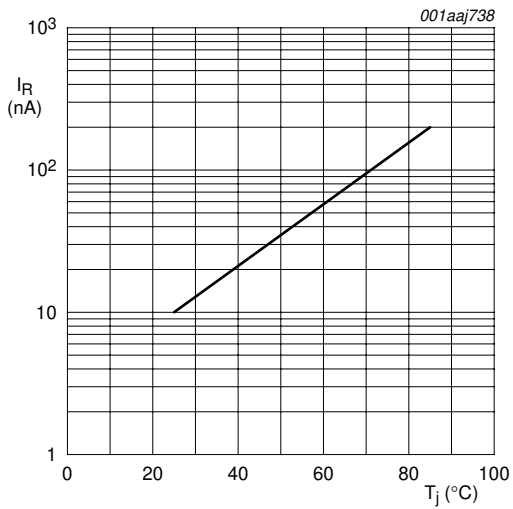
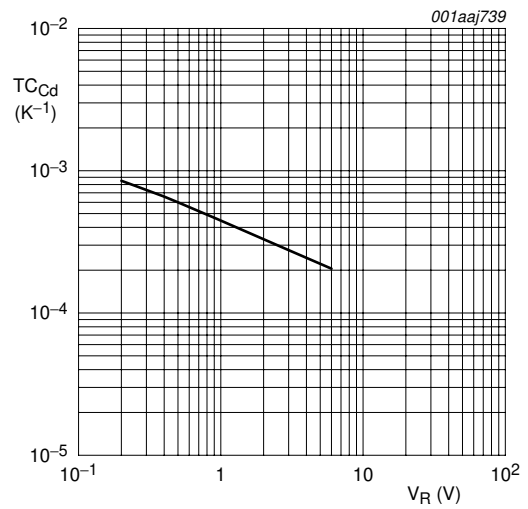


Fig 3. Reverse current as a function of junction temperature; maximum values



$T_j = 0 \text{ }^\circ\text{C} \text{ to } 85 \text{ }^\circ\text{C}.$

Fig 4. Temperature coefficient of diode capacitance as a function of reverse voltage; typical values

7. Package outline

Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm

SOD882T

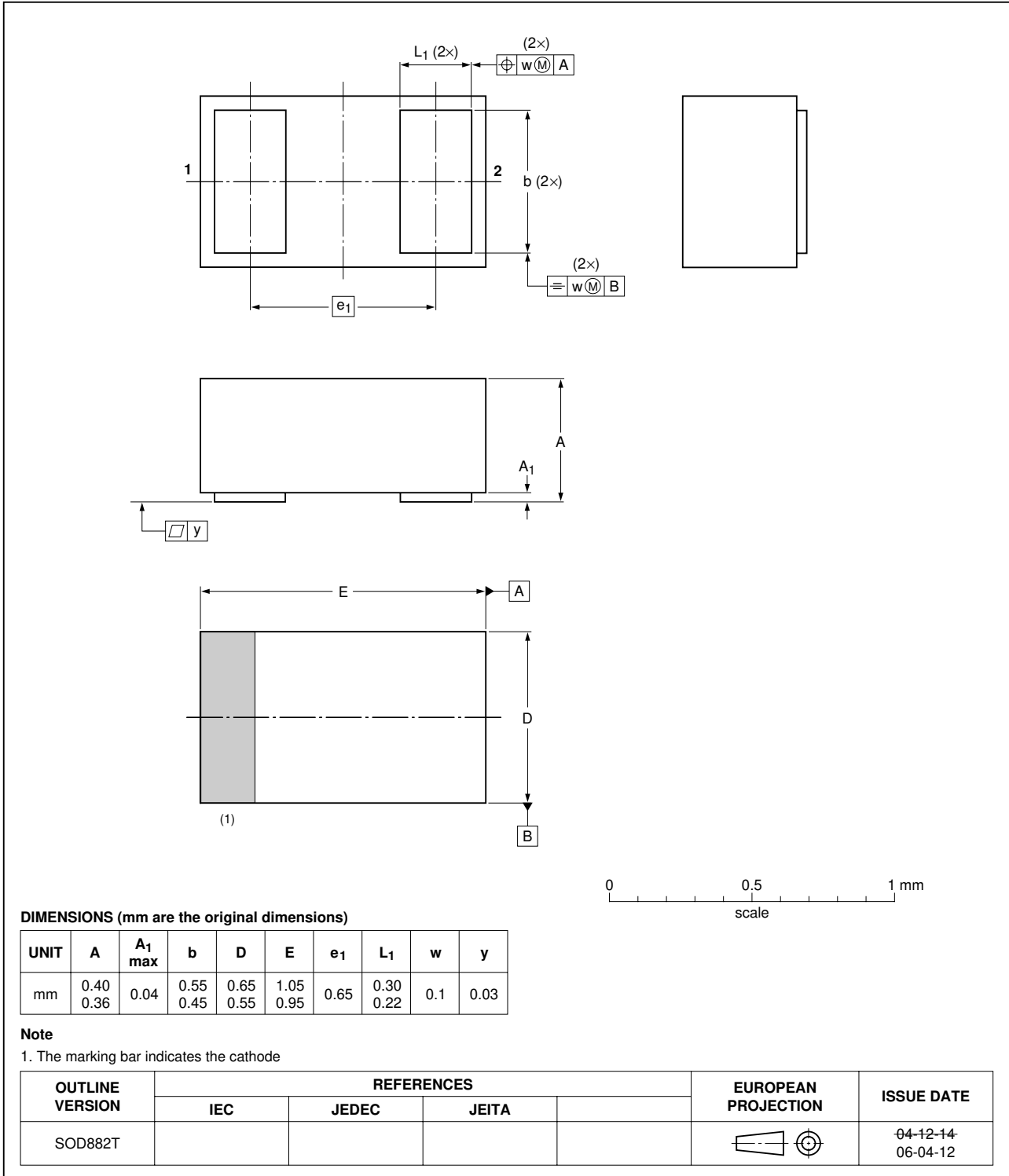


Fig 5. Package outline SOD882T

8. Abbreviations

Table 6. Abbreviations

Acronym	Description
SMD	Surface Mounted Device
VHF	Very High Frequency

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BB187LX_1	20090219	Product data sheet	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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